SINGLE-ENDED, ANALOG-INPUT 24-BIT, 96-kHz STEREO A/D CONVERTER

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas

Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

FEATURES

- 24-Bit Delta-Sigma Stereo A/D Converter
- Single-Ended Voltage Input: 3 Vp-p
- High Performance:
 - THD + N: –93 dB (Typical)
 - SNR: 99 dB (Typical)
 - Dynamic Range: 99 dB (Typical)
- Oversampling Decimation Filter:
 - Oversampling Frequency: ×64
 - Pass-Band Ripple: ±0.05 dB
 - Stop-Band Attenuation: -65 dB
 - On-Chip High-Pass Filter: 0.91 Hz (48 kHz)
- Flexible PCM Audio Interface
 - Master/Slave Mode Selectable
 - Data Formats: 24-Bit I²S, 24-Bit Left-Justified
- Power Down and Reset by Halting System Clock
- Analog Antialias LPF Included
- Sampling Rate: 8 kHz-96 kHz
- System Clock: 256 f_s, 384 f_s, 512 f_s
- Dual Power Supplies:
 - 5-V for Analog
 - 3.3-V for Digital
- Package: 14-Pin TSSOP

APPLICATIONS

- DVD Recorder
- Digital TV
- AV Amplifier/Receiver
- MD Player
- CD Recorder
- Multitrack Receiver
- Electric Musical Instrument

DESCRIPTION

The PCM1808 is high-performance, low-cost, single-chip, stereo analog-to-digital converter with single-ended analog voltage input. The PCM1808 uses a delta-sigma modulator with 64-times oversampling and includes a digital decimation filter and high-pass filter that removes the dc component of the input signal. For various applications, the PCM1808 supports master and slave mode and two data formats in serial audio interface.

The PCM1808 supports the power-down and reset function by means of halting the system clock.

The PCM1808 is suitable for wide variety of cost-sensitive consumer applications where good performance and operation with a 5-V analog supply and 3.3-V digital supply is required. The PCM1808 is fabricated using a highly advanced CMOS process and is available in a small, 14-pin TSSOP package.

System Two, Audio Precision are trademarks of Audio Precision, Inc. All other trademarks are the property of their respective owners.





PCM1808



SLES177A-APRIL 2006-REVISED AUGUST 2006



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

ABSOLUTE MAXIMUM RATINGS

over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

	PCM1808
Analog supply voltage, V _{CC}	–0.3 V to 6.5 V
Digital supply voltage, V _{DD}	–0.3 V to 4 V
Ground voltage differences, AGND, DGND	±0.1 V
Digital input voltage, LRCK, BCK, DOUT	-0.3 V to (V _{DD} + 0.3 V) < 4 V
Digital input voltage, SCKI, MD0, MD1, FMT	–0.3 V to 6.5 V
Analog input voltage, V _{IN} L, V _{IN} R, V _{REF}	-0.3 V to (V _{CC} + 0.3 V) < 6.5 V
Input current (any pins except supplies)	±10 mA
Ambient temperature under bias, T _A	–40°C to 125°C
Storage temperature, T _{stg}	–55°C to 150°C
Junction temperature, T _J	150°C
Lead temperature (soldering)	260°C, 5 s
Package temperature (reflow, peak)	260°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

RECOMMENDED OPERATING CONDITIONS

over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Analog supply voltage, V _{CC}		4.5	5	5.5	V
Digital supply voltage, V _{DD}		2.7	3.3	3.6	V
Analog input voltage, full scale (-0 dB)	$V_{CC} = 5 V$		3		Vp-p
Digital input logic family		TTL	. compatible		
Digital input clock frequency, system clock		2.048		49.152	MHz
Digital input clock frequency, sampling clock		8		96	kHz
Digital output load capacitance				20	pF
Operating free-air temperature, T _A		-40		85	°C

ELECTRICAL CHARACTERISTICS

All specifications at $T_A = 25^{\circ}C$, $V_{CC} = 5 \text{ V}$, $V_{DD} = 3.3 \text{ V}$, master mode, $f_S = 48 \text{ kHz}$, system clock = 512 f_S , 24-bit data, unless otherwise noted

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
	Resolution			24		Bits	
DATA FOR	RMAT						
	Audio data interface format		l²S,	left-justified			
	Audio data bit length			24		Bits	
	Audio data format		MSB-first	, 2s compleme	ent		
s	Sampling frequency		8	48	96	kHz	
		256 f _S	2.048	12.288	24.576		
	System clock frequency	384 f _S	3.072	18.432	36.864	MHz	
		512 f _S	4.096	24.576	49.152		
NPUT LO	GIC						
V _{IH} (1)			2		V_{DD}		
/ _{IL} (1)			0		0.8		
/ _{IH} ⁽²⁾⁽³⁾	Input logic level		2		5.5	VDC	
/ _{IL} ⁽²⁾⁽³⁾			0		0.8		
IH ⁽²⁾		$V_{IN} = V_{DD}$			±10		
L ⁽²⁾	-	$V_{IN} = 0 V$			±10		
H ⁽¹⁾⁽³⁾	Input logic current	$V_{IN} = V_{DD}$		65	100	μA	
IL ⁽¹⁾⁽³⁾		$V_{IN} = 0 V$			±10		
	OGIC						
/ _{ОН} ⁽⁴⁾		$I_{OUT} = -4 \text{ mA}$	2.8				
/ _{OL} ⁽⁴⁾	Output logic level	I _{OUT} = 4 mA			0.5	VDC	
	RACY	1 1					
	Gain mismatch, channel-to-channel			±1	±3	% of FS	
	Gain error			±3	±6	% of FS	
OYNAMIC	PERFORMANCE ⁽⁵⁾						
		$V_{IN} = -0.5 \text{ dB}, \text{ f}_{S} = 48 \text{ kHz}$		-93	-87		
		$V_{IN} = -0.5 \text{ dB}, f_S = 96 \text{ kHz}^{(6)}$		-87			
THD + N	Total harmonic distortion + noise	$V_{IN} = -60 \text{ dB}, f_{S} = 48 \text{ kHz}$		-37		dB	
		$V_{IN} = -60 \text{ dB}, f_S = 96 \text{ kHz}^{(6)}$		-39			
	- .	$f_{\rm S} = 48$ kHz, A-weighted	95	99			
	Dynamic range	$f_{\rm S} = 96$ kHz, A-weighted ⁽⁶⁾		101		dB	
		$f_{\rm S} = 48$ kHz, A-weighted	95	99			
5/N	Signal-to-noise ratio	$f_{\rm S}$ = 96 kHz, A-weighted ⁽⁶⁾		101		dB	
		f _S = 48 kHz	93	97			
	Channel separation	$f_{\rm S} = 96 \text{ kHz}^{(6)}$		91		dB	

Pins 7, 8: LRCK, BCK (Schmitt-trigger input, with 50-kΩ typical pulldown resistor, in slave mode)
 Pin 6: SCKI (Schmitt-trigger input, 5-V tolerant)
 Pins 10–12: MD0, MD1, FMT (Schmitt-trigger input, with 50-kΩ typical pulldown resistor, 5-V tolerant)
 Pins 7–9: LRCK, BCK (in master mode), DOUT

(5) Analog performance specifications are tested using a System Two[™] audio measurement system by Audio Precision[™] with 400-Hz HPF and 20-kHz LPF in RMS mode.

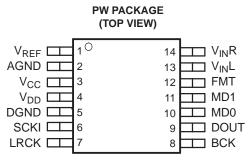
(6) $f_S = 96 \text{ kHz}$, system clock = 256 f_S .

ELECTRICAL CHARACTERISTICS (continued)

All specifications at $T_A = 25^{\circ}$ C, $V_{CC} = 5$ V, $V_{DD} = 3.3$ V, master mode, $f_S = 48$ kHz, system clock = 512 f_S , 24-bit data, unless otherwise noted

	PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALO	G INPUT	<u> </u>			H	
	Input voltage			0.6 V _{CC}		Vp-p
	Center voltage (V _{REF})			0.5 V _{CC}		V
	Input impedance			60		kΩ
	Antialiasing filter frequency response	-3 dB		1.3		MHz
DIGITA	L FILTER PERFORMANCE		i.		i	
	Pass band				0.454 f _S	Hz
	Stop band		0.583 f _S			Hz
	Pass-band ripple				±0.05	dB
	Stop-band attenuation		-65			dB
	Delay time			17.4/f _S		
	HPF frequency response	–3 dB	0.0	19 f _S /1000		
POWER	R SUPPLY REQUIREMENTS					
V _{CC}			4.5	5	5.5	VDC
V _{DD}	Voltage range		2.7	3.3	3.6	VDC
		f _S = 48 kHz, 96 kHz ⁽⁸⁾		8.6	11	mA
I _{CC}		Powered down ⁽⁹⁾		1		μA
	Supply current ⁽⁷⁾	f _S = 48 kHz		5.9	8	mA
I _{DD}		f _S = 96 kHz ⁽⁸⁾		10.2		mA
		Powered down ⁽⁹⁾		150		μA
		f _S = 48 kHz		62	81	mW
	Power dissipation (7)	$f_{\rm S} = 96 \text{ kHz}^{(8)}$		77		mvv
		Powered down ⁽⁹⁾		500		μW
TEMPE	RATURE RANGE	· · · · · · · · · · · · · · · · · · ·			H	
T _A	Operation temperature		-40		85	°C
θ_{JA}	Thermal resistance			170		°C/W

PIN ASSIGNMENTS



P0032-02

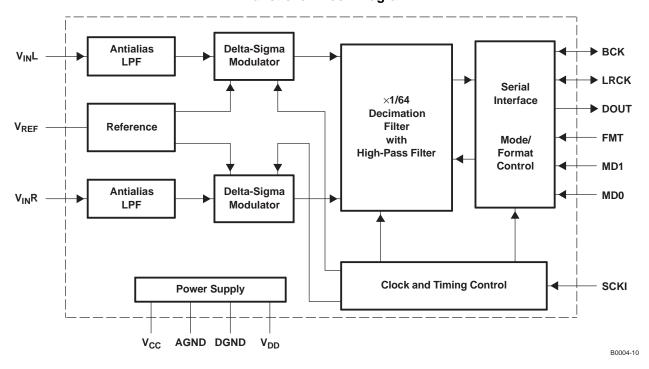
TERMINAL FUNCTIONS

TERM	IINAL	I/O	DESCRIPTION	
NAME	PIN			
AGND	2	-	Analog GND	
BCK	8	I/O	Audio data bit clock input/output ⁽¹⁾	
DGND	5	-	Digital GND	
DOUT	9	0	Audio data digital output	
FMT	12	I	Audio interface format select ⁽²⁾	
LRCK	7	I/O	Audio data latch enable input/output ⁽¹⁾	
MD0	10	I	io interface mode select 0 ⁽²⁾	
MD1	11	I	Audio interface mode select 1 ⁽²⁾	
SCKI	6	I	System clock input; 256 f_S , 384 f_S or 512 $f_S^{(3)}$	
V _{CC}	3	-	Analog power supply, 5-V	
V _{DD}	4	-	Digital power supply, 3.3-V	
V _{IN} L	13	I	Analog input, L-channel	
V _{IN} R	14	I	Analog input, R-channel	
V _{REF}	1	_	Reference voltage decoupling (= 0.5 V _{CC})	

Schmitt-trigger input with internal pulldown (50-kΩ, typical)
 Schmitt-trigger input with internal pulldown (50-kΩ, typical), 5-V tolerant
 Schmitt-trigger input, 5-V tolerant



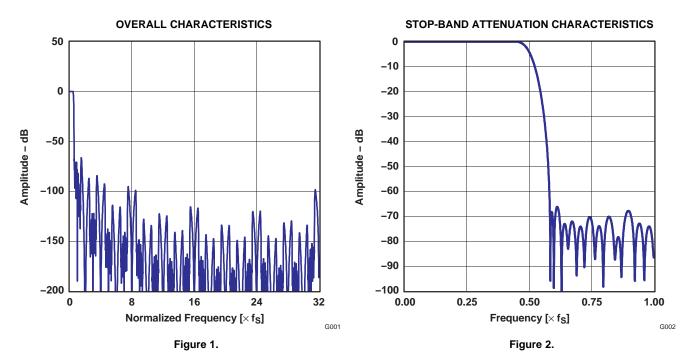
Functional Block Diagram



TYPICAL PERFORMANCE CURVES OF INTERNAL FILTERS

All specifications at $T_A = 25^{\circ}$ C, $V_{CC} = 5$ V, $V_{DD} = 3.3$ V, master mode, $f_S = 48$ kHz, system clock = 512 f_S , 24-bit data, unless otherwise noted.

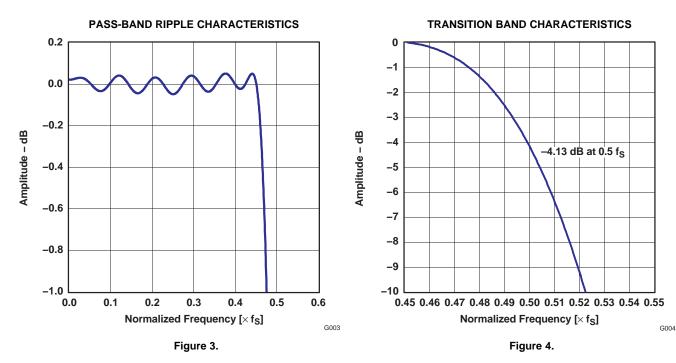
DECIMATION FILTER FREQUENCY RESPONSE



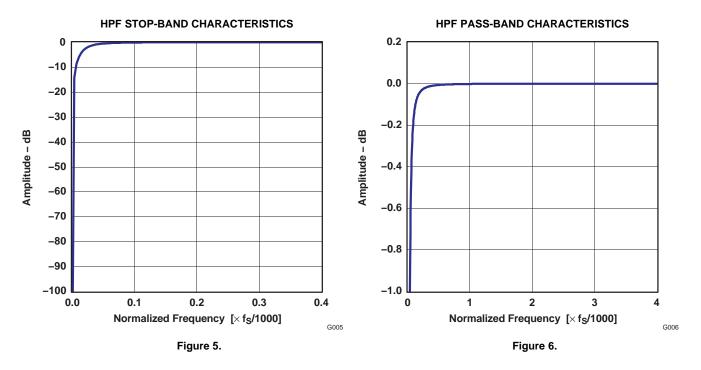
TYPICAL PERFORMANCE CURVES OF INTERNAL FILTERS (Continued)

All specifications at $T_A = 25^{\circ}$ C, $V_{CC} = 5$ V, $V_{DD} = 3.3$ V, master mode, $f_S = 48$ kHz, system clock = 512 f_S , 24-bit data, unless otherwise noted.

DECIMATION FILTER FREQUENCY RESPONSE (Continued)



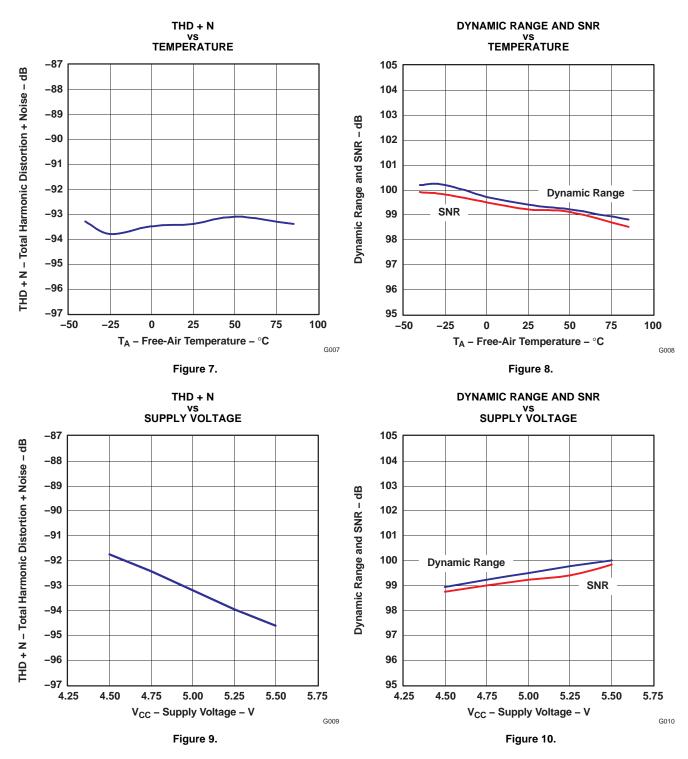
HIGH-PASS FILTER FREQUENCY RESPONSE





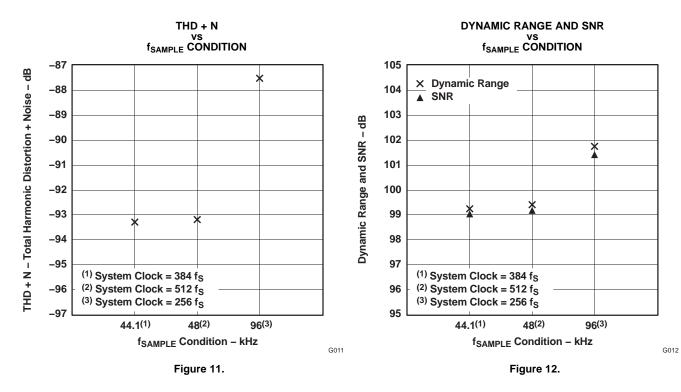
TYPICAL PERFORMANCE CURVES

All specifications at $T_A = 25^{\circ}C$, $V_{CC} = 5 \text{ V}$, $V_{DD} = 3.3 \text{ V}$, master mode, $f_S = 48 \text{ kHz}$, system clock = 512 f_S , 24-bit data, unless otherwise noted.

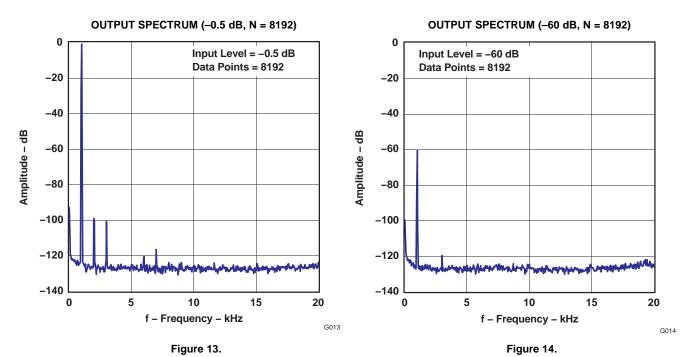


TYPICAL PERFORMANCE CURVES (Continued)

All specifications at $T_A = 25^{\circ}$ C, $V_{CC} = 5$ V, $V_{DD} = 3.3$ V, master mode, $f_S = 48$ kHz, system clock = 512 f_S , 24-bit data, unless otherwise noted.



OUTPUT SPECTRUM



PCM1808

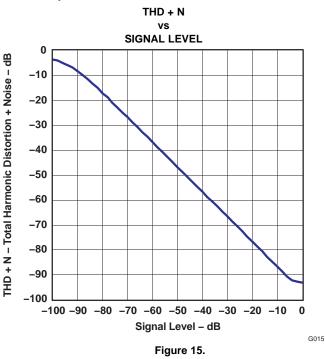


SLES177A-APRIL 2006-REVISED AUGUST 2006

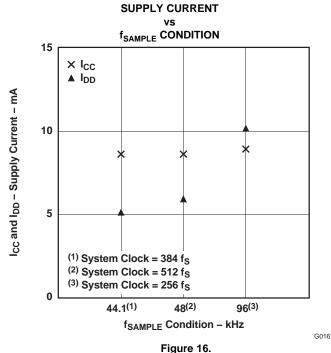
TYPICAL PERFORMANCE CURVES (Continued)

All specifications at $T_A = 25^{\circ}$ C, $V_{CC} = 5$ V, $V_{DD} = 3.3$ V, master mode, $f_S = 48$ kHz, system clock = 512 f_S , 24-bit data, unless otherwise noted.

OUTPUT SPECTRUM (Continued)



SUPPLY CURRENT



SYSTEM CLOCK

The PCM1808 supports 256 f_S , 384 f_S and 512 f_S as system clock, where f_S is the audio sampling frequency. The system clock must be supplied on SCKI (pin 6).

The PCM1808 has a system clock detection circuit which automatically senses if the system clock is operating at 256 f_S , 384 f_S , or 512 f_S in slave mode. In master mode, the system clock frequency must be controlled through the serial control port, which uses MD1 (pin 111) and MD0 (pin 10). The system clock is divided down automatically to generate frequencies of 128 f_S and 64 f_S , which are used to operate the digital filter and the delta-sigma modulator, respectively.

Table 1 shows some typical relationships between sampling frequency and system clock frequency, and Figure 17 shows system clock timing.

SAMPLING FREQUENCY (kHz)	SYSTEM CLOCK FREQUENCY (f _{SCLK}) (MHz)				
	256 f _S	384 f _S	512 f _S		
8	2.048	3.072	4.096		
16	4.096	6.144	8.192		
32	8.192	12.288	16.384		
44.1	11.2896	16.9344	22.5792		
48	12.288	18.432	24.576		
64	16.384	24.576	32.768		
88.2	22.5792	33.8688	45.1584		
96	24.576	36.864	49.152		

Table 1. Sampling Frequency and System Clock Frequency



SYMBOL	PARAMETER	MIN	MAX	UNIT
t _{w(SCKH)}	System clock pulse duration, HIGH	8		ns
t _{w(SCKL)}	System clock pulse duration, LOW	8		ns
	System clock duty cycle	40%	60%	

Figure 17. System Clock Timing

FADE-IN AND FADE-OUT FUNCTIONS

The PCM1808 has fade-in and fade-out functions on DOUT (pin 9) to avoid pop noise, and the functions come into operation in some cases as described in several following sections. The level changes from 0 dB to mute or mute to 0 dB are performed using calculated pseudo S-shaped characteristics with zero-cross detection. Because of the zero-cross detection, the time needed for the fade in and fade out depends on the analog input frequency (f_{in}). It takes 48/ f_{in} until processing is completed. If there is no zero cross during 8192/ f_{S} , DOUT is faded in or out by force during 48/ f_{S} (TIME OUT). Figure 18 illustrates the fade-in and fade-out operation processing.



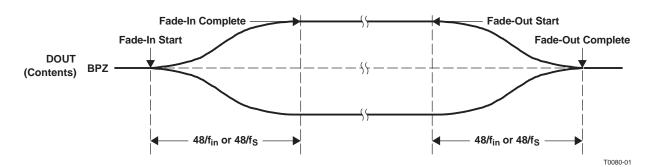
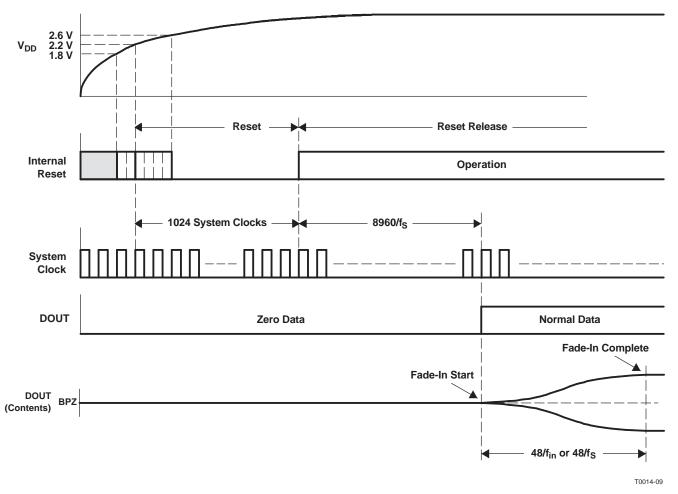


Figure 18. Fade-In and Fade-Out Operations

POWER ON

The PCM1808 has an internal power-on-reset circuit, and initialization (reset) is performed automatically when the power supply (V_{DD}) exceeds 2.2 V (typical). While $V_{DD} < 2.2$ V (typical), and for 1024 system-clock counts after $V_{DD} > 2.2$ V (typical), the PCM1808 stays in the reset state and the digital output is forced to zero. The digital output is valid after the reset state is released and the time of 8960/f_S has elapsed. Because the fade-in operation is performed, it takes additional time of 48/f_{in} or 48/f_S until the data corresponding to the analog input signal is obtained. Figure 19 illustrates the power-on timing and the digital output.



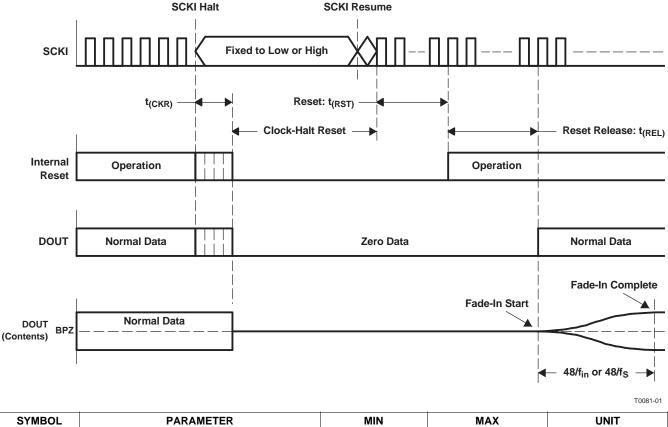


CLOCK-HALT POWER-DOWN AND RESET FUNCTION

The PCM1808 has a power-down and reset function, which is triggered by halting SCKI (pin 6) in both master and slave modes. The function is available anytime after power on. Reset and power down are performed automatically 4 μ s (minimum) after SCKI is halted. While the clock-halt reset is asserted, the PCM1808 stays in the reset and power-down mode, and DOUT (pin 9) is forced to zero. SCKI must be supplied to release the reset and power-down mode. The digital output is valid after the reset state is released and the time of 1024 SCKI + 8960/f_S has elapsed. Because the fade-in operation is performed, it takes additional time of 48/f_{in} or 48/f_S until the level corresponding to the analog input signal is obtained. Figure 20 illustrates the clock-halt reset timing.

To avoid ADC performance degradation, BCK (pin 8) and LRCK (pin 7) are required to synchronize with SCKI within $4480/f_S$ after SCKI is resumed. If it takes more than $4480/f_S$ for BCK and LRCK to synchronize with SCKI, SCKI should be masked until the synchronization is achieved again, taking care of glitch and jitter. See the typical circuit connection diagram, Figure 26.

To avoid ADC performance degradation, the clock-halt reset also should be asserted when system clock SCKIor the audio interface clocks BCK and LRCK (sampling rate f_s) are changed on the fly.



SYMBOL	PARAMETER	MIN	MAX	UNIT
t _(CKR)	Delay time from SCKI halt to internal reset	4		μs
t _(RST)	Delay time from SCKI resume to reset release		1024 SCKI	μs
t _(REL)	Delay time from reset release to DOUT output		8960/f _S	μs

Figure 20. Clock-Halt Power-Down and Reset Timing



SERIAL AUDIO DATA INTERFACE

The PCM1808 interfaces the audio system through LRCK (pin 7), BCK (pin 8), and DOUT (pin 9).

INTERFACE MODE

The PCM1808 supports master mode and slave mode as interface modes, which are selected by MD1 (pin 11) and MD0 (pin 10), as shown in Table 2. MD1 and MD0 must be set prior to power on.

In master mode, the PCM1808 provides the timing of serial audio data communications between the PCM1808 and the digital audio processor or external circuit. While in slave mode, the PCM1808 receives the timing for data transfer from an external controller.

MD1 (Pin 11)	MD0 (Pin 10)	INTERFACE MODE
Low	Low	Slave mode (256 f_S , 384 f_S , 512 f_S autodetection)
Low	High	Master mode (512 f _S)
High	Low	Master mode (384 f _S)
High	High	Master mode (256 f _S)

Table 2. Interface Modes

Master mode

In master mode, BCK and LRCK work as output pins, and these pins are controlled by timing which is generated in the clock circuit of the PCM1808. The frequency of BCK is fixed at 64 BCK/frame.

Slave mode

In slave mode, BCK and LRCK work as input pins. The PCM1808 accepts 64-BCK/frame or 48-BCK/frame format (only for a 384-f_S system clock), not 32-BCK/frame format.

DATA FORMAT

The PCM1808 supports two audio data formats in both master and slave modes. The data formats are selected by FMT (pin 12), as shown in Table 3. Figure 21 illustrates the data formats in slave mode and master mode.

Table 3. Data Format

FORMAT NO.	FMT (Pin 12)	FORMAT
0	Low	I ² S, 24-bit
1	High	Left-justified, 24-bit

TEXAS INSTRUMENTS www.ti.com

FORMAT 0: FMT = LOW

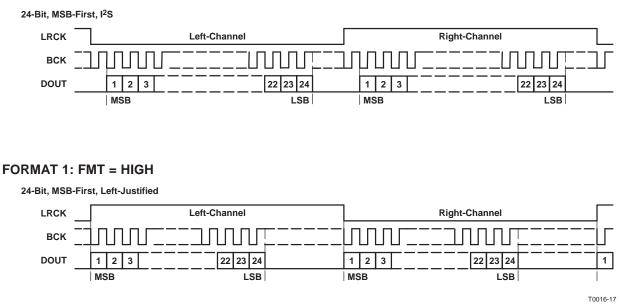
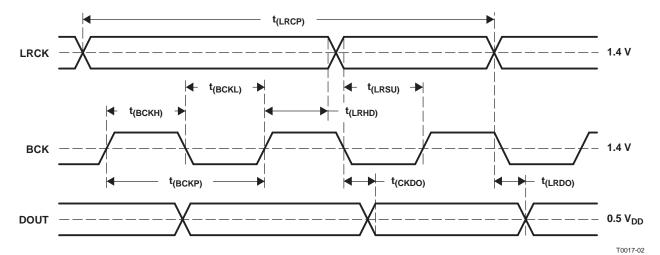


Figure 21. Audio Data Format (LRCK and BCK Work as Inputs in Slave Mode and as Outputs in Master Mode)

INTERFACE TIMING

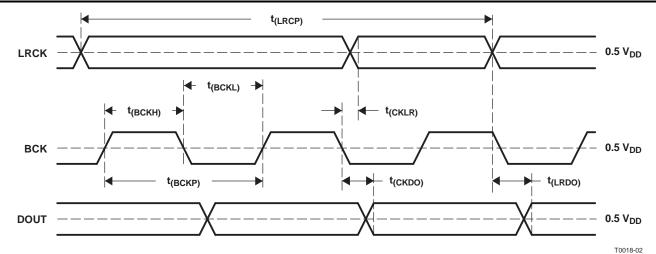
Figure 22 and Figure 23 illustrate the interface timing in slave mode and master mode, respectively.



SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
t _(BCKP)	BCK period	1/(64 f _S)			ns
t _(BCKH)	BCK pulse duration, HIGH	$1.5 imes t_{(SCKI)}$			ns
t _(BCKL)	BCK pulse duration, LOW	$1.5 imes t_{(SCKI)}$			ns
t _(LRSU)	LRCK setup time to BCK rising edge	50			ns
t _(LRHD)	LRCK hold time to BCK rising edge	10			ns
t _(LRCP)	LRCK period	10			μs
t _(CKDO)	Delay time, BCK falling edge to DOUT valid	-10		40	ns
t _(LRDO)	Delay time, LRCK edge to DOUT valid	-10		40	ns
t _r	Rise time of all signals			20	ns
t _f	Fall time of all signals			20	ns

NOTE: Timing measurement reference level is 1.4 V for input and 0.5 V_{DD} for output. Rise and fall times are from 10% to 90% of the input/output signal swing. Load capacitance of DOUT is 20 pF. $t_{(SCKI)}$ is the SCKI period.

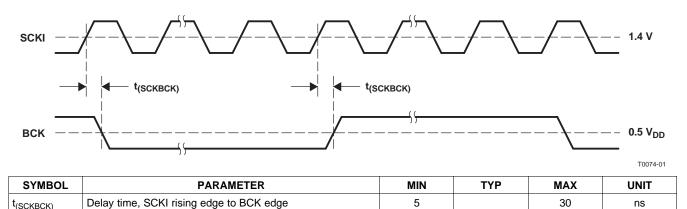
Figure 22. Audio Data Interface Timing (Slave Mode: LRCK and BCK Work as Inputs)



SYMBOL	PARAMETER	MIN	TYP	MAX	UNIT
t _(BCKP)	BCK period	150	1/(64 f _S)	2000	ns
t _(BCKH)	BCK pulse duration, HIGH	65		1200	ns
t _(BCKL)	BCK pulse duration, LOW	65		1200	ns
t _(CKLR)	Delay time, BCK falling edge to LRCK valid	-10		20	ns
t _(LRCP)	LRCK period	10	1/f _S	125	μs
t _(CKDO)	Delay time, BCK falling edge to DOUT valid	-10		20	ns
t _(LRDO)	Delay time, LRCK edge to DOUT valid	-10		20	ns
t _r	Rise time of all signals			20	ns
t _f	Fall time of all signals			20	ns

NOTE: Timing measurement reference level is 0.5 V_{DD} . Rise and fall times are from 10% to 90% of the input/output signal swing. Load capacitance of all signals is 20 pF.

Figure 23. Audio Data Interface Timing (Master Mode: LRCK and BCK Work as Outputs)



 t_(SCKBCK)
 Delay time, SCKI rising edge to BCK edge
 5
 30
 r

 NOTE: Timing measurement reference level is 1.4 V for input and 0.5 V_{DD} for output. Load capacitance of BCK is 20 pF. This timing is applied when SCKI frequency is less than 25 MHz.
 30
 r

Figure 24. Audio Clock Interface Timing (Master Mode: BCK Works as Output)

SYNCHRONIZATION WITH DIGITAL AUDIO SYSTEM

In slave mode, the PCM1808 operates under LRCK (pin 7), synchronized with system clock SCKI (pin 6). The PCM1808 does not require a specific phase relationship between LRCK and SCKI, but does require the synchronization of LRCK and SCKI.

If the relationship between LRCK and SCKI changes more than ± 6 BCKs for 64 BCK/frame (± 5 BCKs for 48 BCK/frame) during one sample period due to LRCK or SCKI jitter, internal operation of the ADC halts within $1/f_s$ and digital output is forced to zero data (BPZ code) until resynchronization between LRCK and SCKI is established.

In the case of changes less than ±5 BCKs for 64 BCK/frame (±4 BCKs for 48 BCK/frame), resynchronization does not occur and the previously described digital output control and discontinuity do not occur.

Figure 25 illustrates the digital output response for loss of synchronization and resynchronization. During undefined data, the PCM1808 can generate some noise in the audio signal. Also, the transition of normal data to undefined data creates a discontinuity in the digital output data, which can generate some noise in the audio signal. The digital output is valid after resynchronization completes and the time of $32/f_S$ has elapsed. Because the fade-in operation is performed, it takes additional time of $48/f_{in}$ or $48/f_S$ until the level corresponding to the analog input signal is obtained. If synchronization is lost during the fade-in operation, the operation stops and DOUT (pin 9) is forced to zero data immediately. The fade-in operation resumes from mute after the time of $32/f_S$ following resynchronization.

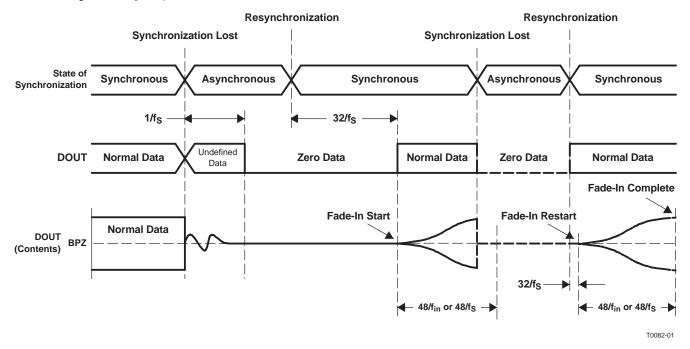
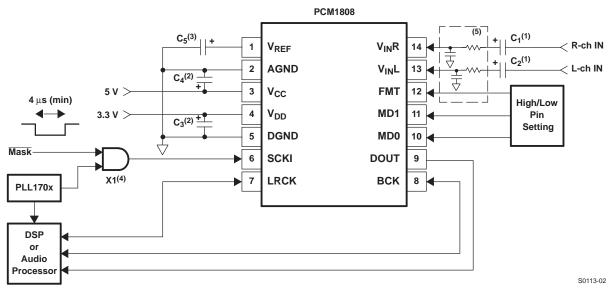


Figure 25. ADC Digital Output for Loss of Synchronization and Resynchronization

APPLICATION INFORMATION

TYPICAL CIRCUIT CONNECTION DIAGRAM

Figure 26 is a typical circuit connection diagram. The antialiasing low-pass filters are integrated on the analog inputs, $V_{IN}L$ and $V_{IN}R$. If the performance of these filters is not adequate for an application, appropriate external antialiasing filters are needed. A passive RC filter (100 Ω and 0.01 μ F to 1 k Ω and 1000 pF) generally is used.



- (1) C1, C2: A 1- μ F electrolytic capacitor gives 2.7 Hz ($\tau = 1 \ \mu$ F × 60 k Ω) cutoff frequency for the input HPF in normal operation and requires a power-on settling time with a 60-ms time constant in the power-on initialization period.
- (2) C3, C4: Bypass capacitors, 0.1-µF ceramic and 10-µF electrolytic, depending on layout and power supply
- (3) C5: 0.1- μ F ceramic and 10- μ F electrolytic capacitors are recommended.
- (4) X1: X1 masks the system clock input when using the clock-halt reset function with external control.
- (5) Optional external antialiasing filter could be required, depending on the application.

Figure 26. Typical Circuit Connection Diagram

BOARD DESIGN AND LAYOUT CONSIDERATIONS

V_{CC}, V_{DD} PINS

The digital and analog power supply lines to the PCM1808 should be bypassed to the corresponding ground pins with both 0.1- μ F ceramic and 10- μ F electrolytic capacitors as close to the pins as possible to maximize the dynamic performance of the ADC.

AGND, DGND PINS

To maximize the dynamic performance of the PCM1808, the analog and digital grounds are not internally connected. These grounds should have low impedance to avoid digital noise feedback into the analog ground. They should be connected directly to each other under the PCM1808 package to reduce potential noise problems.

V_{IN}L, V_{IN}R PINS

 $V_{IN}L$ and $V_{IN}R$ are single-ended inputs. The antialias low-pass filters are integrated on these inputs to remove the high-frequency noise outside the audio band. If the performance of these filters is not adequate for an application, appropriate external antialiasing filters are required. A passive RC filter (100 Ω and 0.01 μ F to 1 k Ω and 1000 pF) is generally used.



APPLICATION INFORMATION (continued)

V_{REF} PIN

To ensure low source impedance of the ADC references, 0.1- μ F ceramic and 10- μ F electrolytic capacitors are recommended between V_{REF} and AGND. These capacitors should be located as close as possible to the V_{REF} pin to reduce dynamic errors on the ADC references.

DOUT PIN

The DOUT pin has a large load-drive capability, but if the DOUT line is long, locating a buffer near the PCM1808 and minimizing load capacitance is recommended to minimize the digital-analog crosstalk and maximize the dynamic performance of the ADC.

SYSTEM CLOCK

The quality of the system clock can influence dynamic performance, as the PCM1808 operates based on a system clock. Therefore, it may be necessary to consider the system clock duty, jitter, and the time difference between system clock transition and BCK or LRCK transition in slave mode.

24-Jan-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish		Op Temp (°C)		Samples
	(1)		Drawing			(2)		(3)		(4)	
PCM1808PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCM1808	Samples
PCM1808PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCM1808	Samples
PCM1808PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCM1808	Samples
PCM1808PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	PCM1808	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Only one of markings shown within the brackets will appear on the physical device.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



www.ti.com

PACKAGE OPTION ADDENDUM

24-Jan-2013

OTHER QUALIFIED VERSIONS OF PCM1808 :

• Automotive: PCM1808-Q1

NOTE: Qualified Version Definitions:

• Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal	
-----------------------------	--

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
PCM1808PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

26-Jan-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
PCM1808PWR	TSSOP	PW	14	2000	367.0	367.0	35.0

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



A. An integration of the information o

Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.

Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.

E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconne	ectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated